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**INTERCONNECTION HIGH DENSITY TEST CONNECTOR
PARTICULARLY MEANT FOR THE VERIFICATION OF INTEGRATED
CIRCUITS**

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The current invention concerns an interconnection high-density test connector particularly meant for the verification of integrated circuits, comprising a plate that supports a multiplicity of conductive spindles, one end of which forms a contact zone with the electronic circuit to be tested and the other end of which forms a contact zone with a linking plate with a means of connection with a test equipment; the conductive spindles have a form capable of ensuring a flexibility that includes a longitudinal component, characterized by the fact that the spindles have a succession of at least three curved sections (4, 5, 6) in alternate directions extended in both sides by mobile straight segments according to a degree of freedom in axial translation, with the spindles inserted in the frontal plates.

Diagram of the summary: Figure 1